ABSOLUTE MAXIMUM RATINGS

Supply Voltage (V _{CC} to V _{EE})		
All Other Pins(V _{CC} + 0.3V) to	o (VEE - 0.3V)	
Current into IN_+, IN	±25mA	
Output Short-Circuit Duration	Continuous	
Continuous Power Dissipation ($T_A = +70^{\circ}C$)		Op
5-Pin SC70 (derate 2.5mW/°C above +70°C)	200mW	Ju
5-Pin SOT23 (derate 7.1mW/°C above +70°C)	571mW	Sto
8-Bump UCSP (derate 4.7mW/°C above +70°C)	379mW	Le

8-Pin µMAX (derate 4.10mW/°C above +70°C	C)330mW
8-Pin SO (derate 5.88mW/°C above +70°C).	471mW
14-Pin SO (derate 8.33mW/°C above +70°C)	667mW
14-Pin TSSOP (derate 6.3mW/°C above +70°	°C)500mW
Operating Temperature Range	40°C to +85°C
Junction Temperature	+150°C
Storage Temperature Range	65°C to +150°C
Lead Temperature (soldering, 10s)	+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

(V_{CC} = 1.8V to 5.5V, V_{EE} = V_{CM} = 0, V_{OUT} = V_{CC}/2, R_L = 100k Ω connected to V_{CC}/2, T_A = +25°C, unless otherwise noted.) (Note 1)

PARAMETER	SYMBOL		CONDITIONS	MIN	ТҮР	МАХ	UNITS
Supply Voltage Range	Vcc	Inferred from I	1.8		5.5	V	
Quiescent Supply Current		$V_{\rm CC} = 1.8V$			100	210	
(Per Amplifier)	lQ	$V_{CC} = 5.0V$			100	255	μA
Input Offact Valtage	Vee	MAX4291			±400	±2500	
Input Offset Voltage	Vos	MAX4292/MAX	X4294		±200	±1200	μV
Input Bias Current	IB	VCC = 5.0V, 0	$\leq V_{CM} \leq 5.0V$		±15	±60	nA
Input Offset Current	los	$V_{CC} = 5.0V, 0$	$\leq V_{CM} \leq 5.0V$		±1	±7	nA
Differential Input Resistance	RIN	V _{IN+} - V _{IN-} <	$ V_{IN+} - V_{IN-} < 10 \text{mV}$		0.75		MΩ
Input Common-Mode Voltage Range	V _{CM}	Inferred from CMRR test		0		V _{CC}	V
		Tested for $0 \le V_{CM} \le$	MAX4291	50	80		dB
Common-Mode Rejection Ratio	CMRR	1.8V; V _{CC} = 1.8V	MAX4292/MAX4294	57	80		UD
	Civitat	Tested for $0 \le V_{CM} \le$ 5.0V, $V_{CC} = 5.0V$	MAX4291	60	90		dB
			MAX4292/MAX4294	66	90		UD
Power-Supply Rejection Ratio	PSRR			77	100		dB

ELECTRICAL CHARACTERISTICS (continued)

(V_{CC} = 1.8V to 5.5V, V_{EE} = V_{CM} = 0, V_{OUT} = V_{CC}/2, R_L = 100k Ω connected to V_{CC}/2, T_A = +25°C, unless otherwise noted.) (Note 1)

PARAMETER	SYMBOL		CONDITIONS	MIN	TYP	МАХ	UNITS
Large-Signal Voltage Gain	Av	V _{CC} = 1.8V	$\label{eq:RL} \begin{array}{l} R_L = 100 k\Omega, \\ 0.02 V \leq V_{OUT} \leq V_{CC} - 0.02 V \end{array}$	80	120		
		VCC - 1.0V	$\label{eq:RL} \begin{split} R_L &= 2k\Omega, \\ 0.1V \leq V_{OUT} \leq V_{CC} - 0.1V \end{split}$	80	110		- dB
		V _{CC} = 5.0V	$\label{eq:RL} \begin{array}{l} R_L = 100 k\Omega, \\ 0.02 V \leq V_{OUT} \leq V_{CC} - 0.02 V \end{array}$	80	130		
		VCC = 5.0V	$\label{eq:RL} \begin{split} R_L &= 2k\Omega, \\ 0.1V \leq V_{OUT} \leq V_{CC} - 0.1V \end{split}$	80	120		
Output-Voltage Swing High	V _{OH}	V _{OH} Specified as IV _{CC} - V _{OH} I	$R_L = 100 k\Omega$ to $V_{CC}/2$		2	20	mV
Output-voltage Swing Flight			$R_L = 2k\Omega$ to $V_{CC}/2$		15	40	
Output-Voltage Swing Low	V _{OL}	V _{OL} Specified as IV _{EE} - V _{OL} I	$R_L = 100 k\Omega$ to $V_{CC}/2$		25	80	mV
dipul-voltage Swing Low			$R_L = 2k\Omega$ to $V_{CC}/2$		46	120	
Output Short-Circuit Current	IOUT(SC)	Sourcing or sin	king		20		mA
Channel-to-Channel Isolation	CHISO	Specified at f =	= 10kHz (MAX4292/MAX4294 only)		83		dB
Gain-Bandwidth Product	GBWP				500		kHz
Phase Margin	фМ				65		degrees
Gain Margin	GM				12		dB
Slew Rate	SR				0.2		V/µs
Input Voltage-Noise Density	en	f = 10kHz			70		nV/√Hz
Input Current-Noise Density	in	f = 10kHz			0.05		pA/√Hz
Capacitive-Load Stability		AvcL = 1V/V, n		100		pF	

ELECTRICAL CHARACTERISTICS

 $(V_{CC} = 1.8V \text{ to } 5.5V, V_{EE} = V_{CM} = 0, V_{OUT} = V_{CC}/2, R_L = 100 \text{k}\Omega$ connected to $V_{CC}/2, T_A = T_{MIN}$ to T_{MAX} , unless otherwise noted.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS	MIN	ТҮР	MAX	UNITS
Supply-Voltage Range	Vcc	Inferred from PSRR test	1.8		5.5	V
Quiescent Supply Current		$V_{\rm CC} = 1.8 V$			240	μA
(Per Amplifier)	IQ	$V_{\rm CC} = 5.0 V$			270	μΑ
Input Offset Voltage	Vos	MAX4291			±3000	uV
input Onset voltage	VOS	MAX4292/MAX4294			±2000	μv

Ultra-Small, 1.8V, μPower, Rail-to-Rail Ι/Ο Ορ Amps

ELECTRICAL CHARACTERISTICS (continued)

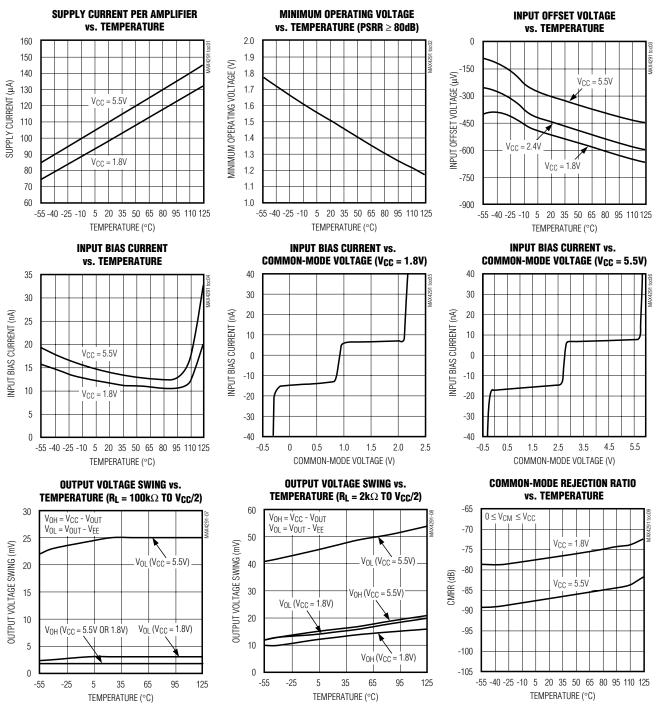
 $(V_{CC} = 1.8V \text{ to } 5.5V, V_{EE} = V_{CM} = 0, V_{OUT} = V_{CC}/2, R_L = 100 \text{k}\Omega$ connected to $V_{CC}/2, T_A = T_{MIN}$ to T_{MAX} , unless otherwise noted.) (Note 1)

PARAMETER	SYMBOL		CONDITIONS	MIN	ТҮР	MAX	UNITS
Input Offset Voltage Drift	TCVOS				1.2		µV/°C
Input Bias Current	IB	Vcc = 5.0V, 0	$\leq V_{CM} \leq 5.0V$			±90	nA
Input Offset Current	los	$V_{CC} = 5.0V, 0$	$\leq V_{CM} \leq 5.0V$			±10	nA
Input Common-Mode Voltage Range	V _{CM}	Inferred from C	CMRR test	0		Vcc	V
		Tested for $0 \le V_{CM} \le 1.8V_{,}$	MAX4291	50			dB
Common-Mode Rejection Ratio	CMRR	$V_{CC} = 1.8V$	MAX4292/MAX4294	53			
	T C	Tested for $0 \le V_{CM} \le 5.0V$, $V_{CC} = 5.0V$	MAX4291	60		d	dB
			MAX4292/MAX4294	62			
Power-Supply Rejection Ratio	PSRR			75			dB
	A.,	Vcc = 1.8V	$\label{eq:RL} \begin{array}{l} R_{L} = 100 \mathrm{k}\Omega, \\ 0.02 \mathrm{V} \leq \mathrm{V}_{OUT} \leq \mathrm{V}_{CC} - 0.02 \mathrm{V} \end{array}$	80			- dB
			$\label{eq:RL} \begin{split} R_L &= 2k\Omega, \\ 0.1V \leq V_{OUT} \leq V_{CC} - 0.1V \end{split}$	80			
Large-Signal Voltage Gain	Av		$\label{eq:RL} \begin{array}{l} R_{L} = 100 \mathrm{k}\Omega, \\ 0.02 \mathrm{V} \leq \mathrm{V}_{OUT} \leq \mathrm{V}_{CC} - 0.02 \mathrm{V} \end{array}$	80			
		$V_{CC} = 5.0V$	$\label{eq:RL} \begin{split} R_L &= 2k\Omega, \\ 0.1V \leq V_{OUT} \leq V_{CC} - 0.1V \end{split}$	80			
Output Voltage Swing High	Maria	V _{OH} Specified as IV _{CC} - V _{OH} I	$R_L = 100 k\Omega$ to $V_{CC}/2$			20	m)/
Output-Voltage Swing High	VOH		$R_L = 2k\Omega$ to $V_{CC}/2$			40	mV
Output-Voltage Swing Low	Vol	Specified as	$R_L = 100 k\Omega$ to $V_{CC}/2$			80	mV
Culput-Vollage Swing LOW	VOL	IVEE - VOLI	$R_L = 2k\Omega$ to $V_{CC}/2$			120	111V

Note 1: All devices are 100% tested at $T_A = +25^{\circ}$ C. All temperature limits are guaranteed by design.

Typical Operating Characteristics

 $(V_{CC} = 2.4V, V_{EE} = V_{CM} = 0, V_{OUT} = V_{CC}/2, no load, T_A = +25^{\circ}C, unless otherwise noted.)$

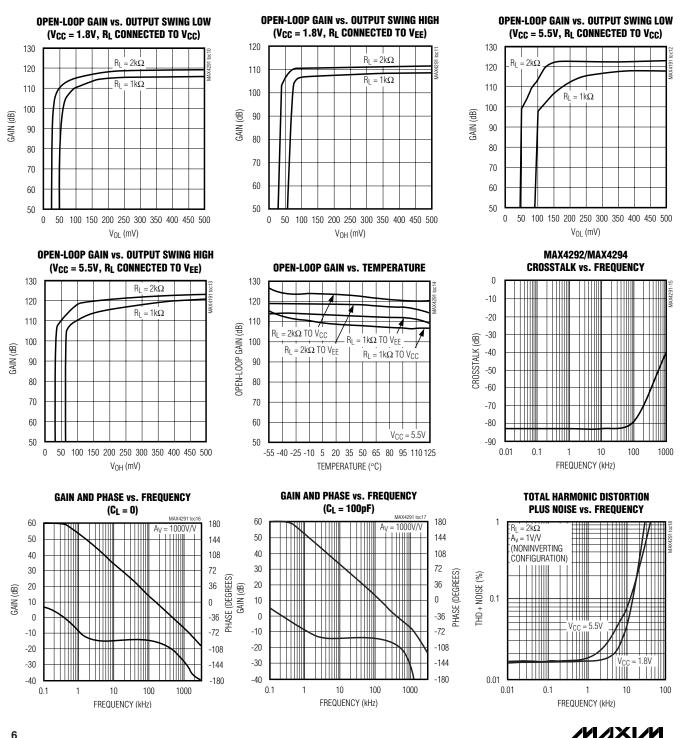


MAX4291/MAX4292/MAX4294

M/IXI/M

Typical Operating Characteristics (continued)

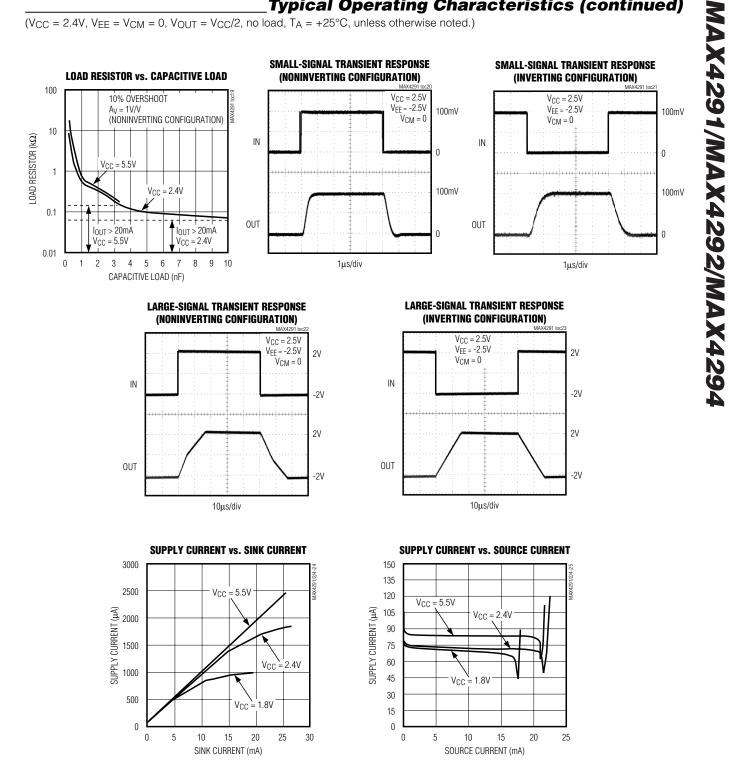
(V_{CC} = 2.4V, V_{EE} = V_{CM} = 0, V_{OUT} = V_{CC}/2, no load, T_A = +25°C, unless otherwise noted.)



MAX4291/MAX4292/MAX4294

Typical Operating Characteristics (continued)

(V_{CC} = 2.4V, V_{EE} = V_{CM} = 0, V_{OUT} = V_{CC}/2, no load, T_A = +25°C, unless otherwise noted.)



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Ultra-Small, 1.8V, μPower, Rail-to-Rail Ι/Ο Ορ Amps

Pin Description

	PIN				FUNCTION		
MAX4291	MAX429	92	MAX4294	NAME			
WAX4291	µMAX/SO	UCSP	MAA4294				
1	_	_		IN+	Noninverting Input		
2	4	C2	11	VEE	Negative Supply. Connect to ground for single-supply operation.		
3	—	_		IN-	Inverting Input		
4	—	_		OUT	Amplifier Output		
5	8	A2	4	V _{CC}	Positive Supply		
_	1, 7	A1, A3	1, 7	OUTA, OUTB	Outputs for Amplifiers A and B		
_	2, 6	B1, B3	2, 6	INA-, INB-	Inverting Inputs to Amplifiers A and B		
_	3, 5	C1, C3	3, 5	INA+, INB+	Noninverting Inputs to Amplifiers A and B		
_		_	8, 14	OUTC, OUTD	Outputs for Amplifiers C and D		
_	—	_	9, 13	INC-, IND-	Inverting Inputs to Amplifiers C and D		
	—		10, 12	INC+, IND+	Noninverting Inputs to Amplifiers C and D		

Detailed Description

Rail-to-Rail Input Stage

The MAX4291/MAX4292/MAX4294 have rail-to-rail inputs and output stages that are specifically designed for low-voltage, single-supply operation in the smallest package possible. The input stage consists of separate NPN and PNP differential stages, which operate together to provide a common-mode range extending to both supply rails. The crossover region of these two pairs occurs halfway between V_{CC} and V_{EE}. The input offset voltage is typically $\pm 200\mu$ V (MAX4292/MAX4294). Low operating supply voltage, low supply current, rail-to-rail common-mode input range, and rail-to-rail outputs make this family of operational amplifiers (op amps) an excellent choice for precision or general-purpose, low-voltage, battery-powered systems.

Since the input stage consists of NPN and PNP pairs, the input bias current changes polarity as the commonmode voltage passes through the crossover region. Match the effective impedance seen by each input to reduce the offset error caused by input bias currents flowing through external source impedances (Figures 1a and 1b).

The combination of high-source impedance plus input capacitance (amplifier input capacitance plus stray

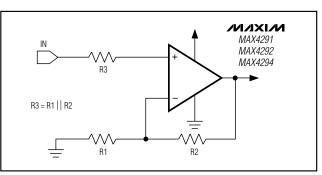


Figure 1a. Minimizing Offset Error Due to Input Bias Current (Noninverting)

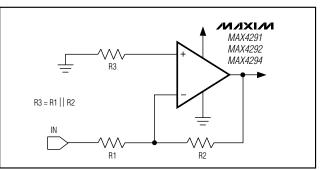


Figure 1b. Minimizing Offset Error Due to Input Bias Current (Inverting)

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Ultra-Small, 1.8V, µPower, Rail-to-Rail I/O Op Amps

Table 1. MAX4291 Characteristics with Typical Battery Systems

BATTERY TYPE	RECHARGE- ABLE	VFRESH (V)	Vend-of-life (V)	CAPACITY, AA SIZE (mA-h)	MAX4291 OPERATING TIME IN NORMAL MODE (h)
Alkaline (2 cells)	No	3.0	1.8	2000	20,000
Nickel-Cadmium (2 cells)	Yes	2.4	1.8	750	7500
Lithium-Ion (1 cell)	Yes	3.5	2.7	1000	10,000
Nickel-Metal- Hydride (2 cells)	Yes	2.4	1.8	1000	10,000

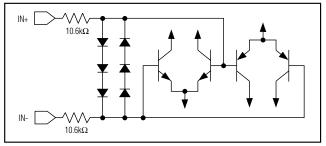


Figure 2. Input Protection Circuit

capacitance) creates a parasitic pole that produces an underdamped signal response. Reducing input capacitance or placing a small capacitor across the feedback resistor improves response in this case.

The MAX4291/MAX4292/MAX4294 family's inputs are protected from large differential input voltages by internal 10.6k Ω series resistors and back-to-back triplediode stacks across the inputs (Figure 2). For differential input voltages (much less than 1.8V), input resistance is typically 0.75M Ω . For differential input voltages greater than 1.8V, input resistance is around 21.2k Ω , and the input bias current can be approximated by the following equation:

$$I_{\text{BIAS}} = \frac{(V_{\text{DIFF}} - 1.8V)}{21.2k\Omega}$$

In the region where the differential input voltage approaches 1.8V, the input resistance decreases exponentially from 0.75M Ω to 21.2k Ω as the diode block begins to conduct. Conversely, the bias current increases with the same curve.

In unity-gain configuration, high slew-rate input signals may capacitively couple to the output through the triplediode stacks.

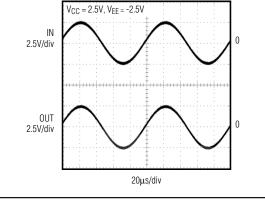


Figure 3. Rail-to-Rail Input/Output Voltage Range

Rail-to-Rail Output Stage

The MAX4291/MAX4292/MAX4294 output stage can drive up to a $2k\Omega$ load and still swing to within 46mV of the rails. Figure 3 shows the output-voltage swing of a MAX4291 configured as a unity-gain buffer, powered from a $\pm 2.5V$ supply. The output for this setup typically swings from (VEE + 25mV) to (VCC - 2mV) with a 100k\Omega load.

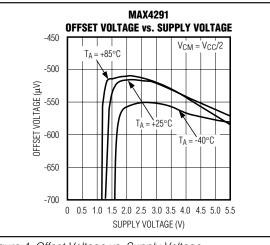
Applications Information

Power-Supply Considerations

The MAX4291/MAX4292/MAX4294 operate from a single 1.8V to 5.5V supply (or dual $\pm 0.9V$ to $\pm 2.75V$ supplies) and consume only 100µA of supply current per amplifier. A high power-supply rejection ratio of 100dB allows the amplifiers to be powered directly off a decaying battery voltage, simplifying design and extending battery life.

The MAX4291/MAX4292/MAX4294 are ideally suited for use with most battery-powered systems. Table 1 lists a







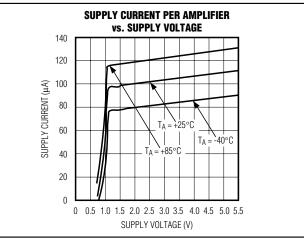


Figure 5. Supply Current per Amplifier vs. Supply Voltage

variety of typical battery types showing voltage when fresh, voltage at end-of-life, capacity, and approximate operating time from a MAX4291 (assuming nominal conditions).

Although the amplifiers are fully guaranteed over temperature for operation down to a 1.8V single supply, even lower voltage operation is possible in practice. Figures 4 and 5 show the offset voltage and supply current as a function of supply voltage and temperature.

Load-Driving Capability

The MAX4291/MAX4292/MAX4294 are fully guaranteed over temperature and supply voltage range to drive a maximum resistive load of $2k\Omega$ to V_{CC}/2, although heavier loads can be driven in many applications. The rail-to-rail output stage of the amplifier can be modeled

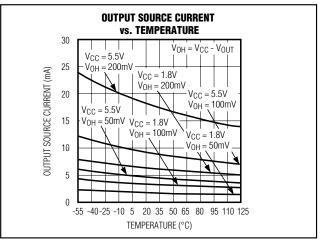


Figure 6a. Output Source Current vs. Temperature

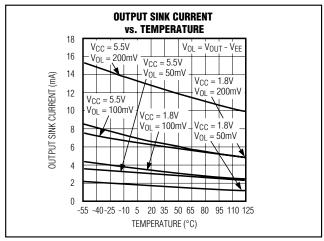


Figure 6b. Output Sink Current vs. Temperature

as a current source when driving the load toward V_{CC}, and as a current sink when driving the load toward V_{EE}. The limit of this current source/sink varies with supply voltage, ambient temperature, and lot-to-lot variations of the units.

Figures 6a and 6b show the typical current source and sink capabilities of the MAX4291/MAX4292/MAX4294 family as a function of supply voltage and ambient temperature. The contours on the graph depict the output current value, based on driving the output voltage to within 50mV, 100mV, and 200mV of either power-supply rail.

For example, a MAX4291 running from a single 1.8V supply, operating at $T_A = +25^{\circ}C$ can source 3.5mA to

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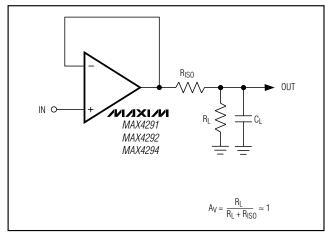


Figure 7a. Using a Resistor to Isolate a Capacitive Load from the Op Amp

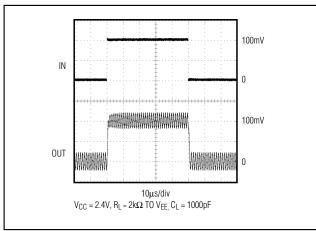


Figure 7b. Pulse Response Without Isolating Resistor

within 100mV of V_CC and is capable of driving a 485Ω load resistor to V_EE:

$$R_L = \frac{(1.8V - 0.1V)}{3.5mA} = 485\Omega$$
 to V_{EE}

The same application can drive a 220 k Ω load resistor when terminated in VCC/2 (0.9V in this case).

Driving Capacitive Loads

The MAX4291/MAX4292/MAX4294 are unity-gain stable for loads up to 100pF (see the Load Resistor vs. Capacitive Load graph in the *Typical Operating Characteristics*). Applications that require greater capacitive-drive capability should use an isolation

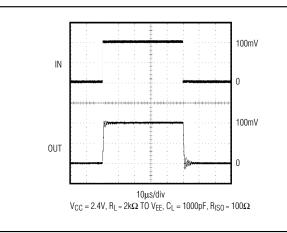


Figure 7c. Pulse Response with Isolating Resistor (100 Ω)

resistor between the output and the capacitive load (Figure 7). Note that this alternative results in a loss of gain accuracy because R_{ISO} forms a voltage divider with the load resistor.

Power-Supply Bypassing and Layout

The MAX4291/MAX4292/MAX4294 family operates from either a single 1.8V to 5.5V supply or dual \pm 0.9V to \pm 2.75V supplies. For single-supply operation, bypass the power supply with a 100nF capacitor to V_{EE} (in this case GND). For dual-supply operation, both the V_{CC} and the V_{EE} supplies should be bypassed to ground with separate 100nF capacitors.

Good PC board layout techniques optimize performance by decreasing the amount of stray capacitance at the op amp's inputs and output. To decrease stray capacitance, minimize trace lengths and widths by placing external components as close as possible to the op amp. Surface-mount components are an excellent choice.

Using the MAX4291/MAX4292/MAX4294 as Comparators

Although optimized for use as operational amplifiers, the MAX4291/MAX4292/MAX4294 can also be used as rail-to-rail I/O comparators. Typical propagation delay depends on the input overdrive voltage, as shown in Figure 8. External hysteresis can be used to minimize the risk of output oscillation. The positive feedback circuit, shown in Figure 9, causes the input threshold to change when the output voltage changes state. The two thresholds create a hysteresis band that can be calculated by the following equations:



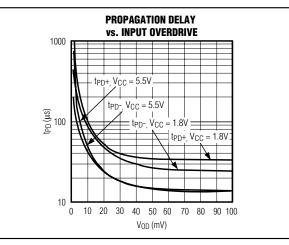


Figure 8. Propagation Delay vs. Input Overdrive

$$\begin{split} V_{HYST} &= V_{HI} - V_{LO} \\ V_{HI} &= \left[1 \, + \, \frac{R1}{R2} \, + \, \frac{R1}{R_{HYST}} \right] V_{REF} \\ V_{LO} &= V_{HI} - \left(\frac{R1}{R_{HYST}} \right) V_{CC} \end{split}$$

When the output of the comparator is low, the supply current increases. The output stage has biasing circuitry to monitor the output current. When the amplifier is used as a comparator, the output stage is overdriven and the current through the biasing circuitry increases to maximum. For the MAX4291, typical supply currents increase to 1.5mA with V_{CC} = 1.8V and to 9mA when V_{CC} = 5.0V (Figure 10).

Using the MAX4291/MAX4292/MAX4294 as Low-Power Current Monitors

The MAX4291/MAX4292/MAX4294 are ideal for applications powered from a two-cell battery stack. Figure 11 shows an application circuit in which the MAX4291 is used for monitoring the current of a two-cell battery stack. In this circuit, a current load is applied, and the voltage drop at the battery terminal is sensed.

The voltage on the load side of the battery stack is equal to the voltage at the emitter of Q1 due to the feedback loop containing the op amp. As the load current increases, the voltage drop across R1 and R2 increases. Thus, R2 provides a fraction of the load current (set by the ratio of R1 and R2) that flows into the

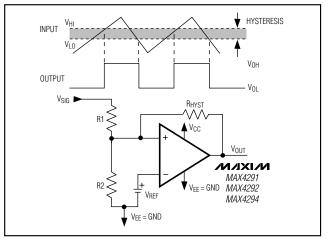


Figure 9. Hysteresis Comparator Circuit

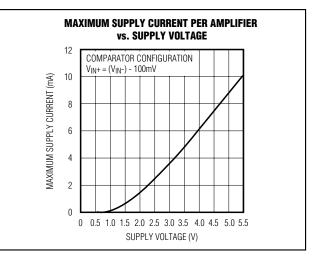


Figure 10. Maximum Supply Current per Amplifier vs. Supply Voltage

emitter of the PNP transistor. Neglecting PNP base current, this current flows into R3, producing a ground-referenced voltage proportional to the load current. To minimize errors, scale R1 to give a voltage drop that is large enough in comparison to the op amp's Vos.

Calculate the output voltage of the application using the following equation:

$$V_{OUT} = \left[I_{LOAD} \times \left(\frac{R1}{R2}\right)\right] \times R3$$

For a 1V output and a current load of 50mA, the choice of resistors can be R1 = 2 Ω , R2 = 100k Ω , and R3 = 1M Ω .

UCSP Information

Layout Issues

Design the layout for the IC to be as compact as possible to minimize parasitics. The UCSP uses a bump pitch of 0.5mm (19.7mil) and bump diameter of 0.3 (~12mil). Therefore, lay out the solder-pad spacing on 0.5mm (19.7mil) centers, using a pad size of 0.25mm (~10mil) and a solder mask opening of 0.33mm (13mil). Round or square pads are permissible. Connect multiple vias from the ground plane as close to the ground pins as possible.

Install capacitors as close as possible to the IC supply voltage pin. Place the ground end of these capacitors near the IC GND pins to provide a low-impedance return path for the signal current.

Prototype Chip Installation

Alignment keys on the PC board, around the area where the chip is located, will be helpful in the prototype assembly process. It is better to align the chip on the board before any other components are placed, and then place the board on a hot plate or hot surface until the solder starts melting. Remove the board from the hot plate without disturbing the position of the chip and let it cool down to room temperature before processing the board further.

UCSP Reliability The UCSP represents a unique packaging form factor that may not perform as well as a packaged product through traditional mechanical reliability tests. UCSP reliability is integrally linked to the user's assembly methods, circuit board material, and usage environment. The user should closely review these areas when considering use of a UCSP.

Performance through operating-life test and moisture resistance remains uncompromised. The wafer-fabrication process primarily determines the performance. Mechanical stress performance is a greater consideration for UCSPs. UCSPs are attached through direct solder contact to the user's PC board, foregoing the inherent stress relief of a packaged product lead frame. Solder-joint contact integrity must be considered. Comprehensive reliability tests have been performed and are available upon request. In conclusion, the UCSP performs reliably through environmental stresses.

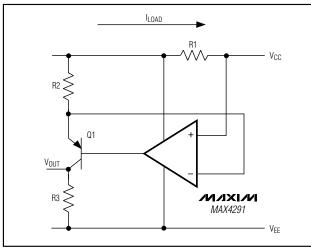
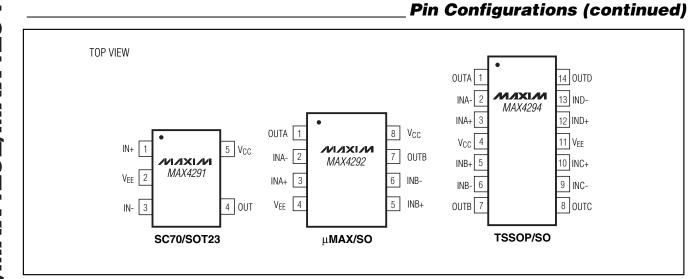


Figure 11. Current Monitor for a 2-Cell Battery Stack

Marking Information



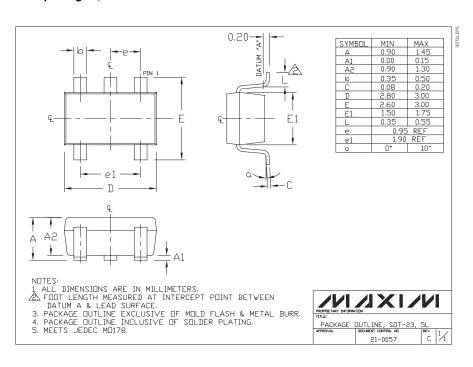


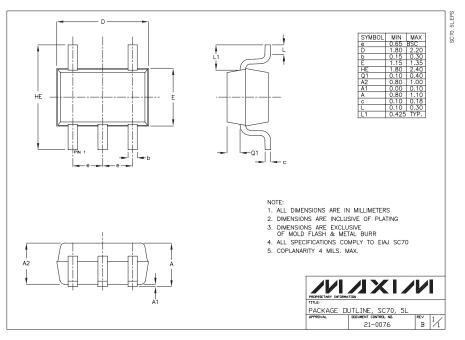
Chip Information

MAX4291 TRANSISTOR COUNT: 149 MAX4292 TRANSISTOR COUNT: 356 MAX4294 TRANSISTOR COUNT: 747 PROCESS: BICMOS

Package Information

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to www.maxim-ic.com/packages.)





Ultra-Small, 1.8V, μPower, Rail-to-Rail Ι/Ο Ορ Amps

Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to **www.maxim-ic.com/packages**.)

INCHES

A1 0.002 0.006 A2 0.030 0.037

0.005 0.007

0.0256 BSC

0.116 0.120

0.016 0.026

0.0207 BSC

0.116 0.120

MIN MAX

0.043

DIM

А

b 0.010

С

D

F

L 0.016 α 0∞

S

MILLIMETERS

MIN MAX

0.05

0.014 0.25

H 0.188 0.198 4.78 5.03

6∞

0.75

0.13

2.95

2.95

0∞

PACKAGE OUTLINE, 8L uMAX/uSOP

21-0036

0.65 BSC

0.41 0.66

0.5250 BSC

1.10

0.15

0.95

0.36

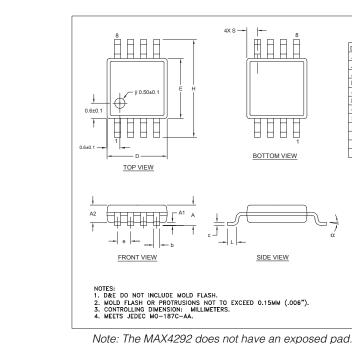
0.18

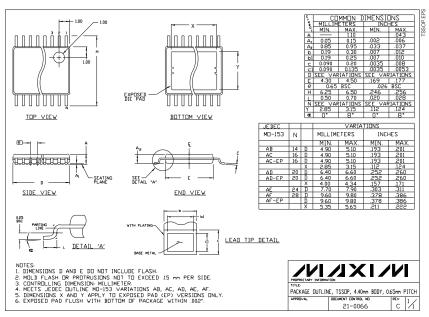
3.05

3.05

6∞

J 1

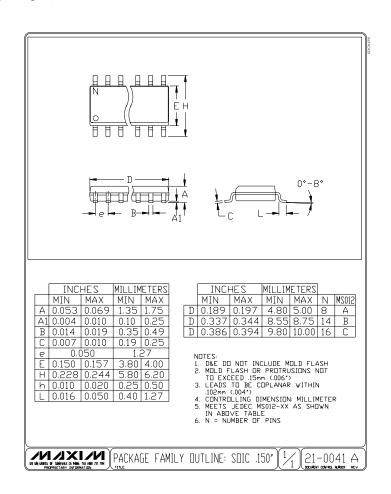




Note: The MAX4294 does not have an exposed pad.

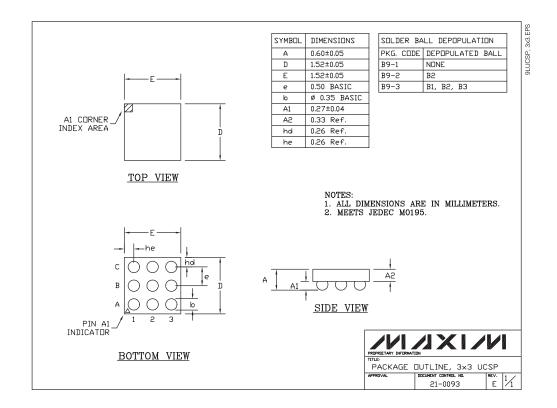
Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to **www.maxim-ic.com/packages**.)



Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to **www.maxim-ic.com/packages**.)



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